

Title (en)

Injection moulding composition containing metal oxide for making metal shapes

Title (de)

Metalloxide enthaltende Spritzgiessmassen zur Herstellung von Metallformkörpern

Title (fr)

Masse à moulage d'injection en contenant des oxides métalliques pour la fabrication d'objets en métaux

Publication

EP 0853995 B1 20011121 (DE)

Application

EP 98100066 A 19980105

Priority

DE 19700277 A 19970107

Abstract (en)

[origin: US6080808A] The molding composition contains, in a flowable binder, from 20 to 50% by vol., based on the total volume of the molding composition, of a powder comprising one or more metal oxides and, if desired, metal carbides and/or metal nitrides which cannot be reduced using hydrogen, where at least 65% by vol. of the powder has a maximum particle size of 0.5 μm and the remainder of the powder has a maximum particle size of 1 μm , and at least 90% by vol. of the powder comprises metal oxides which can be reduced using hydrogen. The metal oxides which can be reduced using hydrogen are Fe_2O_3 , FeO , Fe_3O_4 , NiO , CoO , Co_3O_4 , CuO , Cu_2O , Ag_2O , Bi_2O_3 , WO_3 , MoO_3 , SnO , SnO_2 , CdO , PbO , Pb_3O_4 , PbO_2 or Cr_2O_3 , or mixtures thereof.

IPC 1-7

B22F 3/11; **C22C 1/04**; **C22C 1/05**; **C04B 35/638**; **C04B 35/65**

IPC 8 full level

C04B 35/00 (2006.01); **B22F 3/00** (2006.01); **B22F 3/02** (2006.01); **B22F 3/11** (2006.01); **B22F 3/22** (2006.01); **C04B 35/638** (2006.01); **C04B 35/65** (2006.01); **C22C 1/04** (2006.01); **C22C 1/05** (2006.01)

CPC (source: EP KR US)

B22F 3/001 (2013.01 - EP KR US); **B22F 3/22** (2013.01 - EP US); **B22F 3/225** (2013.01 - EP KR US); **B22F 2998/00** (2013.01 - EP US); **B22F 2998/10** (2013.01 - EP KR US); **B22F 2999/00** (2013.01 - EP KR US)

Cited by

WO2021132854A1; WO2013113880A1; US10961384B2; WO2014170242A1

Designated contracting state (EPC)

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